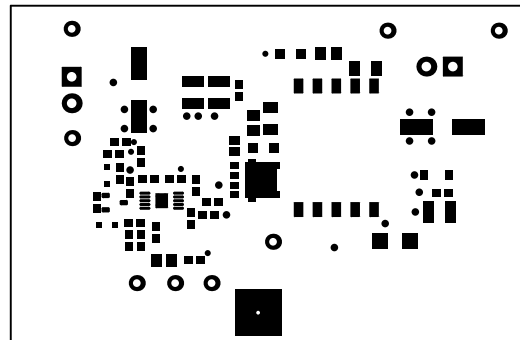
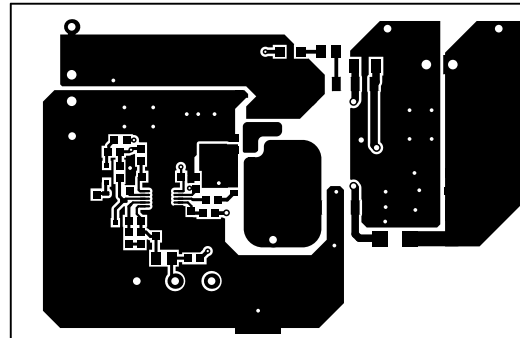


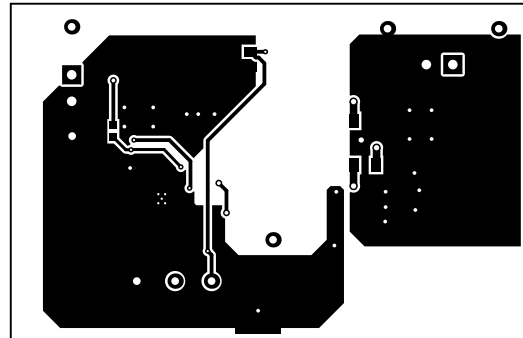
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30308	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: .TID		
PLOT NAME = Top Overlay	GENERATED : 10/17/2017 9:32:25	TEXAS INSTRUMENTS	



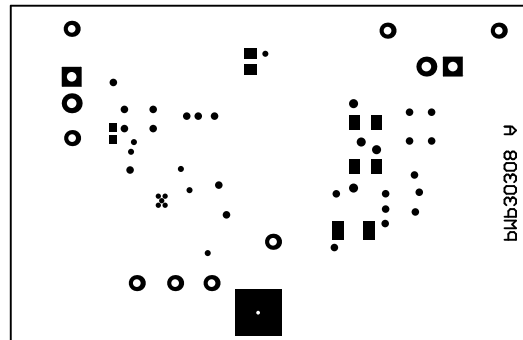
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30308	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: .TID		
PLOT NAME = Top Solder Mask	GENERATED : 10/17/2017 9:32:25	TEXAS INSTRUMENTS	



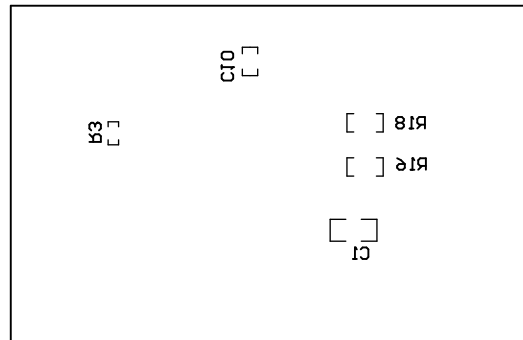
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30308	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: .TID		
PLOT NAME = Top Layer	GENERATED : 10/17/2017 9:32:26	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30308	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: .TID		
PLOT NAME = Bottom Layer	GENERATED : 10/17/2017 9:32:27	TEXAS INSTRUMENTS	

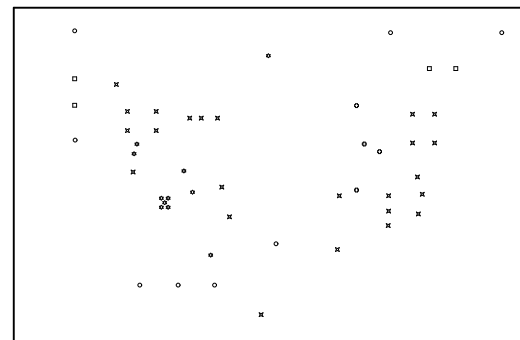


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30308	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: .TID		
PLOT NAME = Bottom Solder Mask	GENERATED : 10/17/2017 9:32:28	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30308	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: .TID		
PLOT NAME = Bottom Overlay	GENERATED : 10/17/2017 9:32:29		TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊗	11	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	24	19.69mil (0.500mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	27.56mil (0.700mm)	PTH	Round	Top Layer - Bottom Layer	
○	8	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
□	4	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer	
	51 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30308	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: .TID		
PLOT NAME = Drill Drawing	GENERATED : 10/17/2017 9:32:30	TEXAS INSTRUMENTS	

10/17/2017 9:32:31



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30308	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: .TID		
PLOT NAME = Board Dimensions	GENERATED : 10/17/2017 9:32:31	TEXAS INSTRUMENTS	

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